

Amendments to the Claims

1. (CURRENTLY AMENDED) A punch-through diode realized as a monolithic ally integrated circuit based on a silicon dice or chip, comprising an n⁺-doped substrate (7) covered with an n-doped epilayer (8); a first p-well (9) and a second p-well (10) implanted into the n-doped epilayer (8) with a distance between the two wells; an n-well (11) penetrating through the n-doped epilayer (8) and into the n⁺-substrate (7); a first p⁺-doped well (13) which connects both the first and the second p-doped wells (9, 10); a polysilicon area (14) on the n-epilayer (8) between the first and the second n-doped wells (9, 10) overlapping the edges of an oxide layer (17); characterized in that a Schottky-metal area (16) is deposited onto at least part of the first p-doped well's (9) surface thus forming a metal (16) - semiconductor (9) - transition and that a second p⁺-doped well (12) is implanted into the first p-doped well (9).

2. (ORIGINAL) A punch-through diode realized as a monolithic ally integrated circuit based on a silicon dice or chip, comprising a p⁺-doped substrate covered with a p-doped epilayer; a first n-well and a second n-well implanted into the p-doped epilayer with a distance between the two wells; a p-well penetrating through the p-doped epilayer and into the p⁺-substrate; a first n⁺-doped well which connects both the first and the second n-doped wells; a polysilicon area on the p-epilayer between the first and the second p-doped wells overlapping the edges of an oxide layer; characterized in that a Schottky-metal area is deposited onto at least part of the first n-doped well's surface thus forming a metal - semiconductor - transition and that a second n⁺-doped well is implanted into the first n-doped well.

3. (CURRENTLY AMENDED) A punch-through diode according to ~~any of the foregoing claims~~, claim 2 characterized in that the monolithic integrated circuit is built on a wafer.

4. (CURRENTLY AMENDED) A punch-through diode according to ~~any of the foregoing claims~~, claim 2 characterized in that the Schottky-metal (16) overlaps the edges of the ambient oxide layer (17).

5. (CURRENTLY AMENDED) A punch-through diode as claimed in ~~any of the foregoing claims~~, claim 2 characterized in that the Schottky-metal area (16) is made of a

material from the group comprising aluminum (Al), titanium (Ti), iron (Fe), chrome (Cr), nickel (Ni), molybdenum (Mo), palladium (Pd).

6. (CURRENTLY AMENDED) A punch-through diode according to ~~any of the foregoing claims~~claim 2 characterized in that the punch-through diode comprises a layer of aluminum on the surface of the n^+ -substrate ~~(7)~~ or p^+ -substrate to enable the contact of a first terminal point of the punch-through diode.

7. (CURRENTLY AMENDED) A punch-through diode according to ~~any of the foregoing~~claim 2 claims characterized in that the punch-through diode comprises a metallized layer above the Schottky-metal area and the polysilicon area that enables the contact to a second terminal point.

8. (CURRENTLY AMENDED) A punch-through diode as claimed in ~~one of the foregoing claims~~claim 2 characterized in that it is realized as a thick film circuit.

9. (CURRENTLY AMENDED) An electronic appliance, comprising a punch-through diode according to ~~any of the former claims~~claim 2.

10. (CURRENTLY AMENDED) Use a punch-through diode according to any of the ~~claims 1 to 8~~claim 1 for over voltage protection in an integrated circuit.

11. (CURRENTLY AMENDED) A method of processing a punch-through diode, comprising the steps of providing an n^+ -substrate ~~(7)~~; generating an n-epilayer ~~(8)~~; forming a first p-doped well ~~(9)~~ in the n-epilayer ~~(8)~~; forming a second p-doped well ~~(10)~~ in the n-epilayer ~~(8)~~; forming an n-doped well ~~(11)~~ penetrating through the epilayer ~~(8)~~ and into the n^+ -substrate ~~(7)~~; forming a p^+ -doped well ~~(13)~~ in the epilayer ~~(8)~~ between the first and the second p-doped wells ~~(9, 10)~~; forming a polysilicon layer ~~(14)~~ between the first and the second p-doped wells ~~(9, 10)~~ overlapping their opposite margin edges; forming an n-doped well ~~(15)~~ under the surface of the epilayer ~~(8)~~ between the first and the second p-doped wells ~~(9, 10)~~; forming a Schottky-metal area ~~(16)~~ on the first p-doped well ~~(9)~~.

12. (ORIGINAL) A method of processing a punch-through diode, comprising the steps of providing a p^+ -substrate; generating a p-epilayer; forming a first and a second n-doped well in the p-epilayer; forming a p-doped well penetrating through the epilayer and into the p^+ -substrate; forming an n^+ -doped well in the epilayer between the first and the second

n-doped wells; forming a polysilicon layer between the first and the second n-doped wells overlapping their opposite margin edges; forming a p-doped well under the surface of the epilayer between the first and the second n-doped wells; forming a Schottky-metal area on the first n-doped well.